



Q1 2025 Investor Conference

May 9th, 2025

Embedded Wisely, Embedded Widely

ememory



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Review of Operations



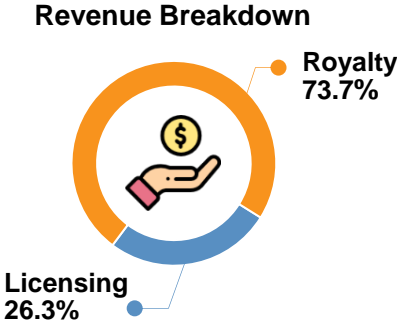
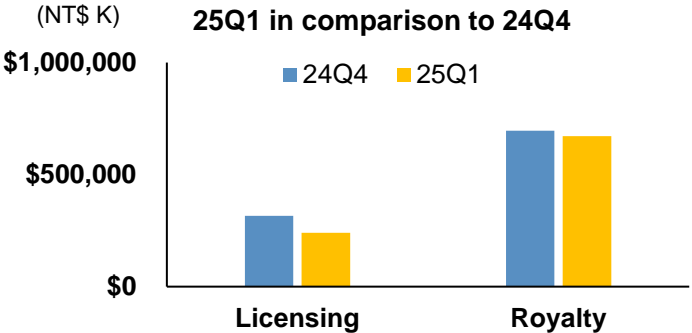
Q1 2025 Financial Results

(thousands of NT dollars)

	Q1 2025	Q4 2024	QoQ	Q1 2024	YoY
Revenue	911,734	1,010,717	-9.8%	802,764	13.6%
Gross Margin	100%	100%	-	100%	-
Operating Expenses	389,387	444,784	-12.5%	382,143	1.9%
Operating Income	522,347	565,933	-7.7%	420,621	24.2%
Operating Margin	57.3%	56.0%	1.3ppts	52.4%	4.9ppts
Net Foreign Exchange Gain	12,151	37,262	-67.4%	69,516	-82.5%
*Net Income	461,706	514,608	-10.3%	430,577	7.2%
Net Margin	49.8%	51.1%	-1.3ppts	52.7%	-2.9ppts
EPS (NT\$)	6.18	6.89	-10.3%	5.77	7.1%
ROE	48.7%	62.5%	-13.8ppts	53.2%	-4.5ppts

*Net income attributable to Shareholders of the Company

Revenue across Different Streams



Revenue

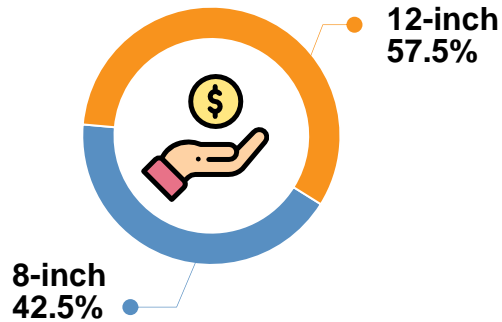
NT\$ Thousands	Q1 2025	Q4 2024	QoQ	Q1 2024	YoY
Licensing	240,217	315,330	-23.8%	228,329	5.2%
Royalty	671,517	695,387	-3.4%	574,435	16.9%
Total	911,734	1,010,717	-9.8%	802,764	13.6%

Revenue by Technology

Technology	Q1 2025								
	Total Revenue			Licensing Revenue			Royalty Revenue		
	% of Q1 Revenue	QoQ	YoY	% of Q1 Licensing	QoQ	YoY	% of Q1 Royalty	QoQ	YoY
NeoBit	25.0%	-4.5%	19.8%	23.6%	-14.0%	18.7%	25.4%	-0.8%	20.2%
NeoFuse	66.2%	-4.4%	12.3%	49.1%	-4.3%	-1.7%	72.4%	-4.4%	16.3%
PUF-Based	1.9%	-75.7%	-4.3%	7.0%	-76.4%	-7.4%	0.1%	1.7%	542.2%
MTP	6.9%	-8.7%	10.7%	20.3%	-11.1%	14.9%	2.1%	0.2%	-1.6%

Royalty Revenue by Wafer Size

Q1 Royalty Breakdown



- 8-inch wafers contributed 42.5% of royalty, up 0.6% sequentially and up 16.1% yearly.
- 12-inch wafers contributed 57.5% of royalty, down 6.2% sequentially but up 17.5% yearly.

Wafer Size	Q1 2025		
	% of Q1	QoQ	YoY
8-Inch	42.5%	0.6%	16.1%
12-Inch	57.5%	-6.2%	17.5%

Future Outlook



Future Outlook

Licensing & Royalty:

■ Licensing:

- Driven by strong demand from foundries and end chip customers coupled with an expanding portfolio of process platforms and more advanced NVM and security-related IP, we expect licensing fees to maintain sustained growth momentum.

■ Royalties:

- We expect royalty revenue to continue its growth trend as the accumulated tape outs in advanced process nodes enter the production stage, along with continued market share gains in mature applications.

Future Outlook

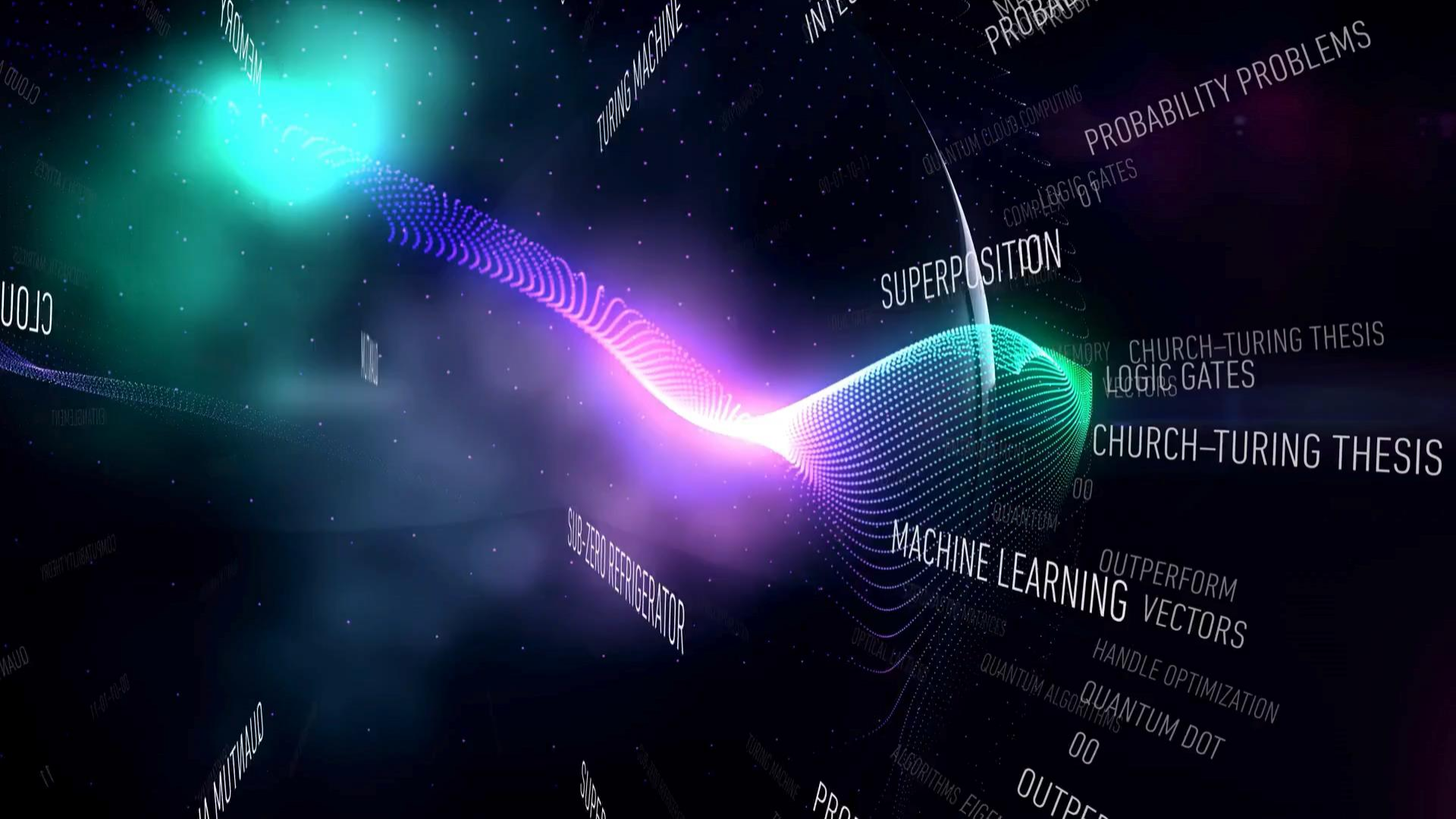
New IP Technology & Business Development:

■ **New IP Technologies:**

- We are developing post-quantum cryptography (PQC) modules and expanding into a full suite of solutions—from PUFrt to PQC PUFcc and PQC PUFhsm—to build the foundational hardware security cores needed for the upcoming decade of quantum migration.

■ **Business Development Platform:**

- Following our recognition as TSMC OIP's Best Embedded Memory IP Partner, we joined the Intel Chiplet Alliance, integrating our OTP/PUF technologies to become a key enabler of Intel's U.S.-based chiplet security innovation solutions.
- At the upcoming Computex, we launched the PUF-based HSM edge server, which serves as the cornerstone of our Security as a Service platform strategy.



TURING MACHINE

INTELLIGENCE

PROBABILITY

PROBABILITY PROBLEMS

QUANTUM CLOUD COMPUTING

LOGIC GATES

SUPERPOSITION

CHURCH-TURING THESIS

LOGIC GATES

CHURCH-TURING THESIS

MACHINE LEARNING

OUTPERFORM VECTORS

HANDLE OPTIMIZATION

QUANTUM DOT

OUTPERFORM

SUB-ZERO REFRIGERATOR

TURING MACHINE

PROBABILITY

ALGORITHMS EIGEN

QUANTUM

QUANTUM

QUANTUM

QUANTUM

QUANTUM



NeoPUF-based HSM Edge Server for PQC Migration

Why Migrate to PQC ?

Future-Proof Security for the Quantum Era

Eliminate risks posed by quantum computing threats

Adopt PQC-Ready HSM Edge Servers

Support both RSA/ECC and PQC crypto algorithms

PQC Migration Steps & Scope



Key Principles:

- Execute Clear Migration Steps
- Prioritize Critical Digital Assets
- Deploy PQC-ready HSM Edge Servers



Select from FIPS 203/204/205
for key exchange & signatures

Validate PQC integration
via software

Track new database
and key system to ensure stability



Assess

Choose PQC

Ensure Agility

PQC Testing

Migration

Monitor



Identify key databases
and prioritize upgrades

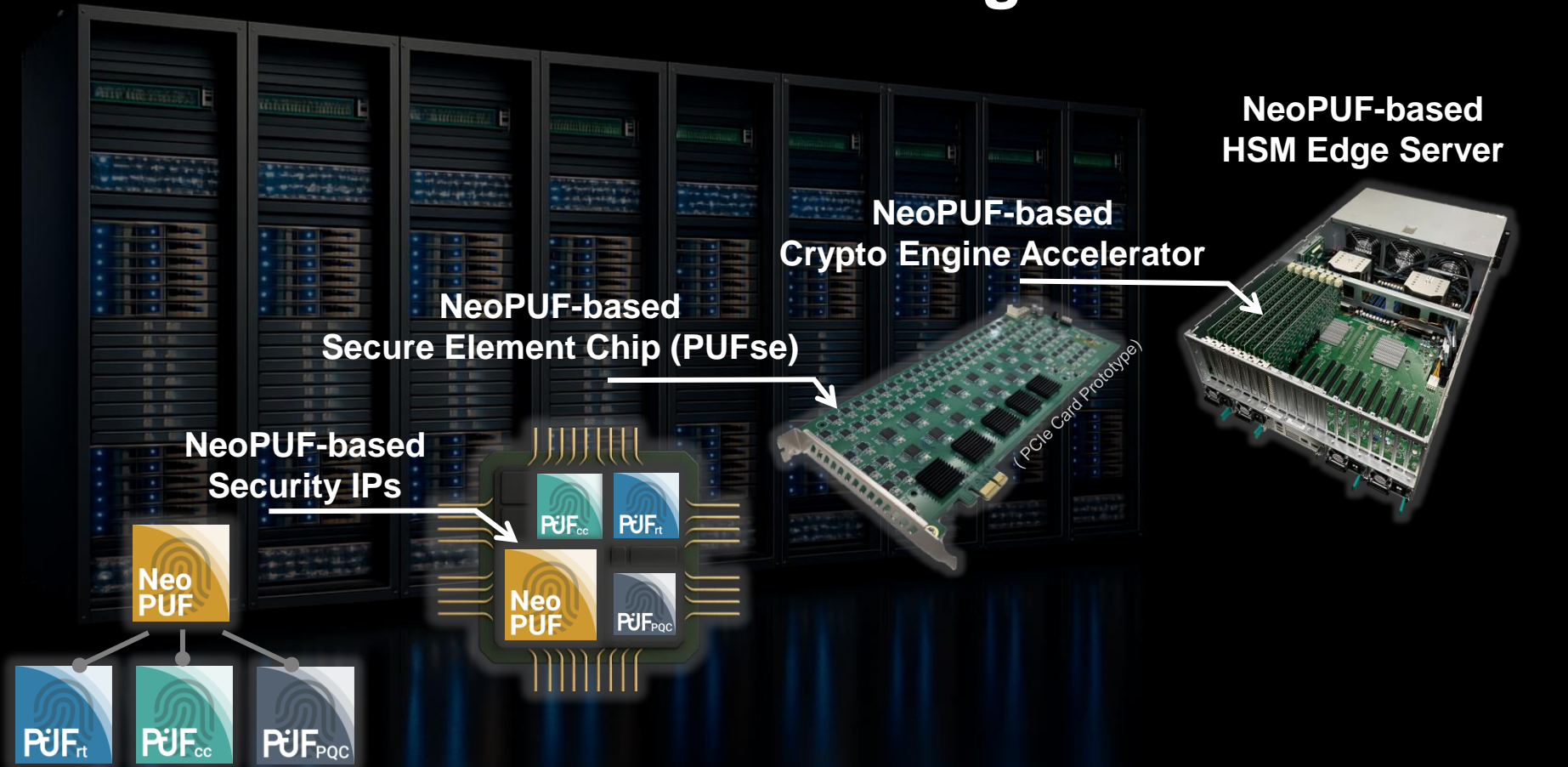


HSM must support PQC, ECC, RSA
(e.g., TLS, IPsec)



- **RSA → PQC**
- **ECC → PQC**
- **AES128 → AES256**

NeoPUF-based HSM Edge Server



NeoPUF-based HSM Edge Server Applications



Financial Services & Banking



E-Commerce & Retail



Healthcare & Pharmaceuticals



Government & Public Sector



Telecommunications



Cloud & Data Centers



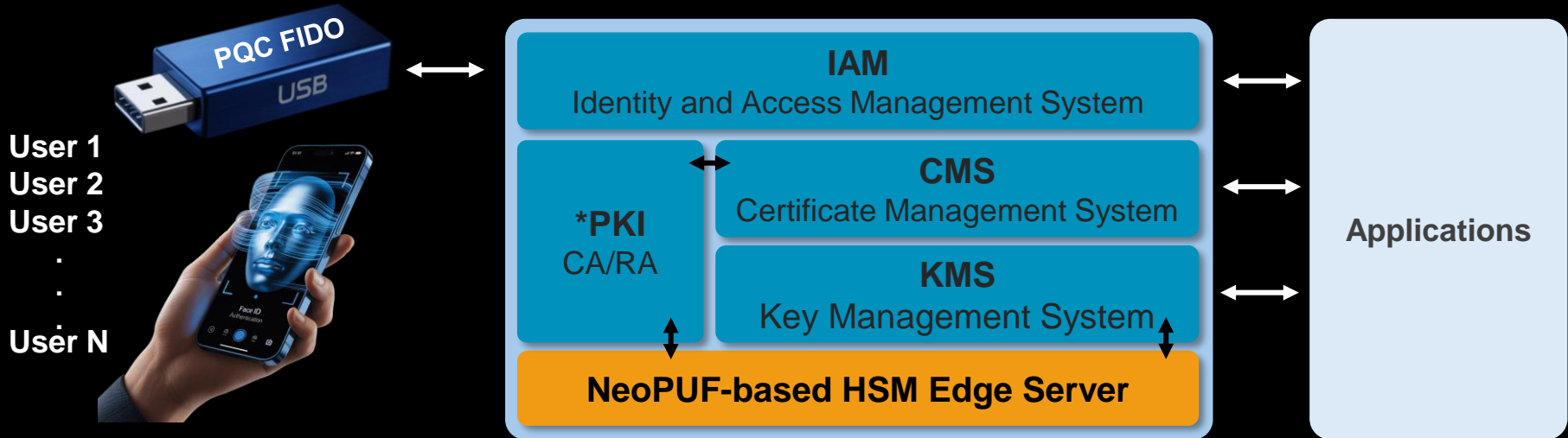
Automotive & Manufacturing

NeoPUF-based PQC Security as a Service

PQC FIDO Key
& Multi-Factor Authentication (MFA)

Zero-Trust NeoPUF-based PQC Security as a Service

For Various
Applications



Q&A



Appendix

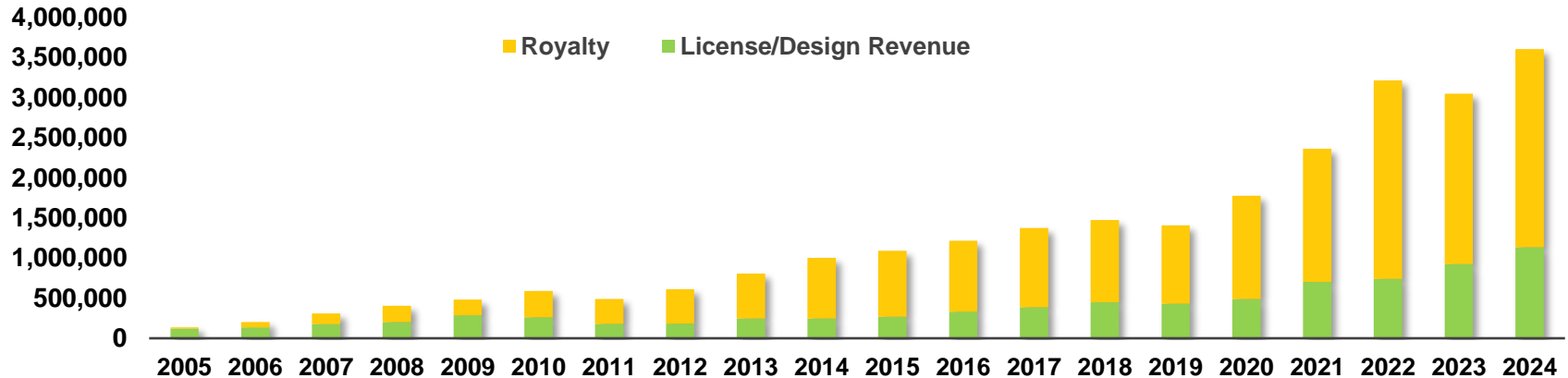


Company Overview

- eMemory is the global leader of embedded non-volatile memory IP

Revenue Trend

(Unit: NT\$ 1,000)



**Founded
In 2000**

Based in Hsinchu, Taiwan.
IPO in 2011. Over 67M wafers
shipped.

**1270+
Patents Issued**

221 pending patents. 367
employees with 68% R&D
personnel.

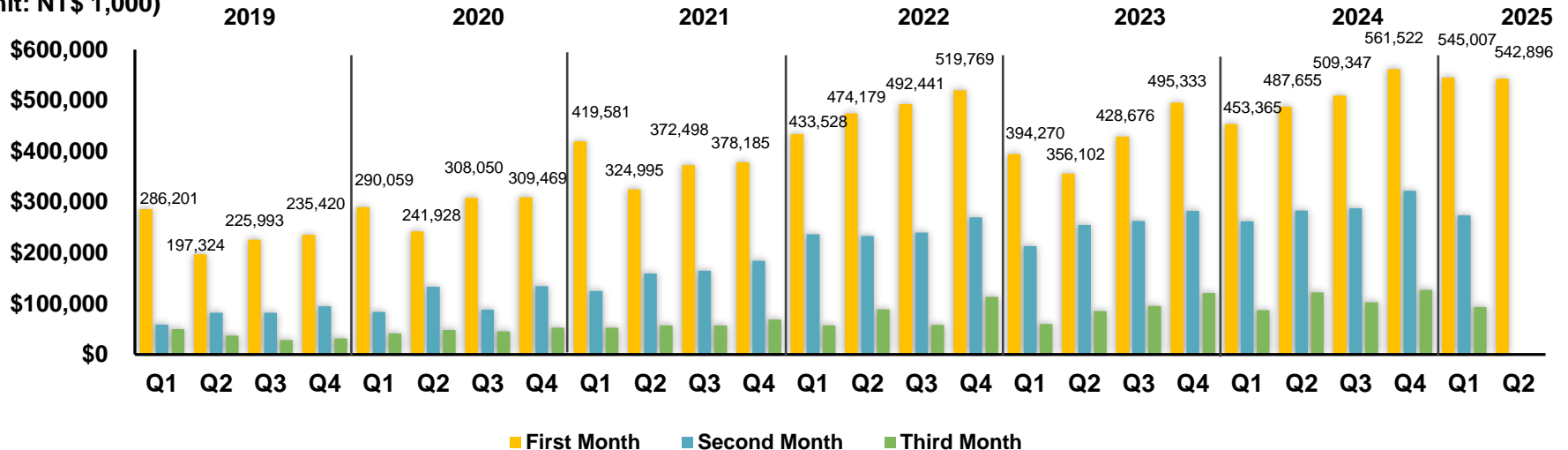
**Best IP Partner
With TSMC**

TSMC Best IP Partner Award
since 2010.

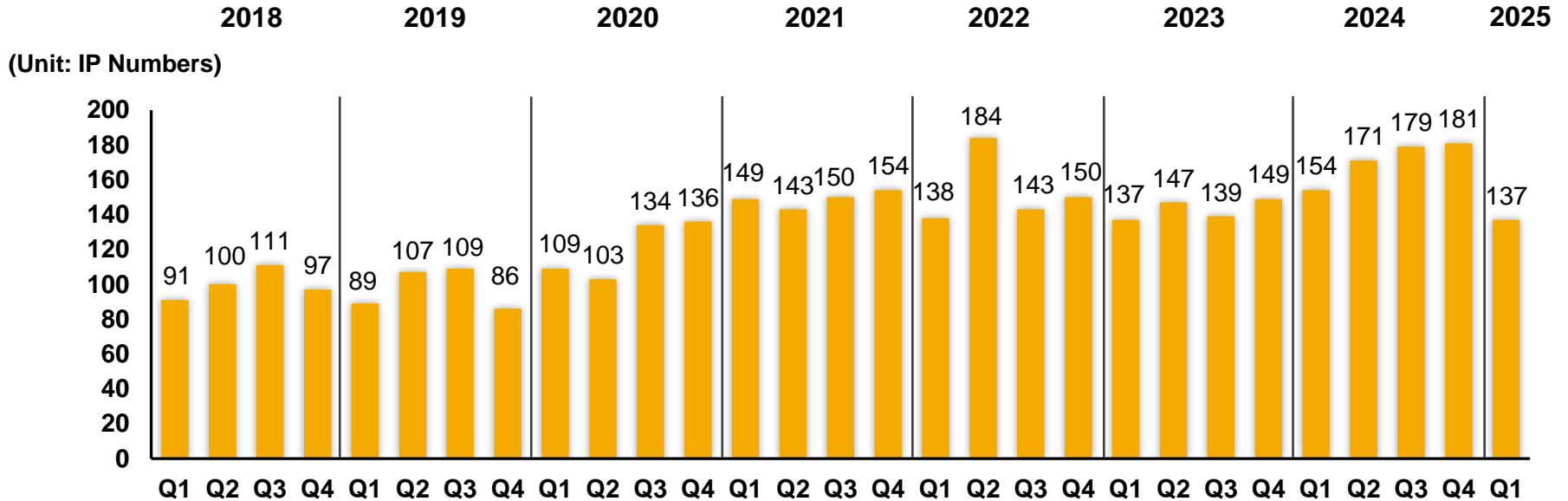
Quarterly Revenue Pattern

- 1st month: Receive **License Fees** of the month and **Royalty** from most foundries on previous quarter's wafer shipments.
- 2nd month: Receive **License Fees** of the month and **Royalty** from other foundries.
- 3rd month: **License Fees** Only.

(Unit: NT\$ 1,000)



Quarterly Number of New Tape-outs



Worldwide Customers

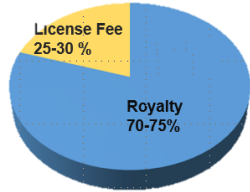
- Our IP solutions are adopted by leading foundries, IDM's and fabless worldwide

Country	Foundry	IDM	Fabless
Taiwan	4	1	350
China	12	0	1361
Korea	4	0	103
Japan	1	9	88
North America	2	2	368
Europe	2	2	237
Others	1	0	127

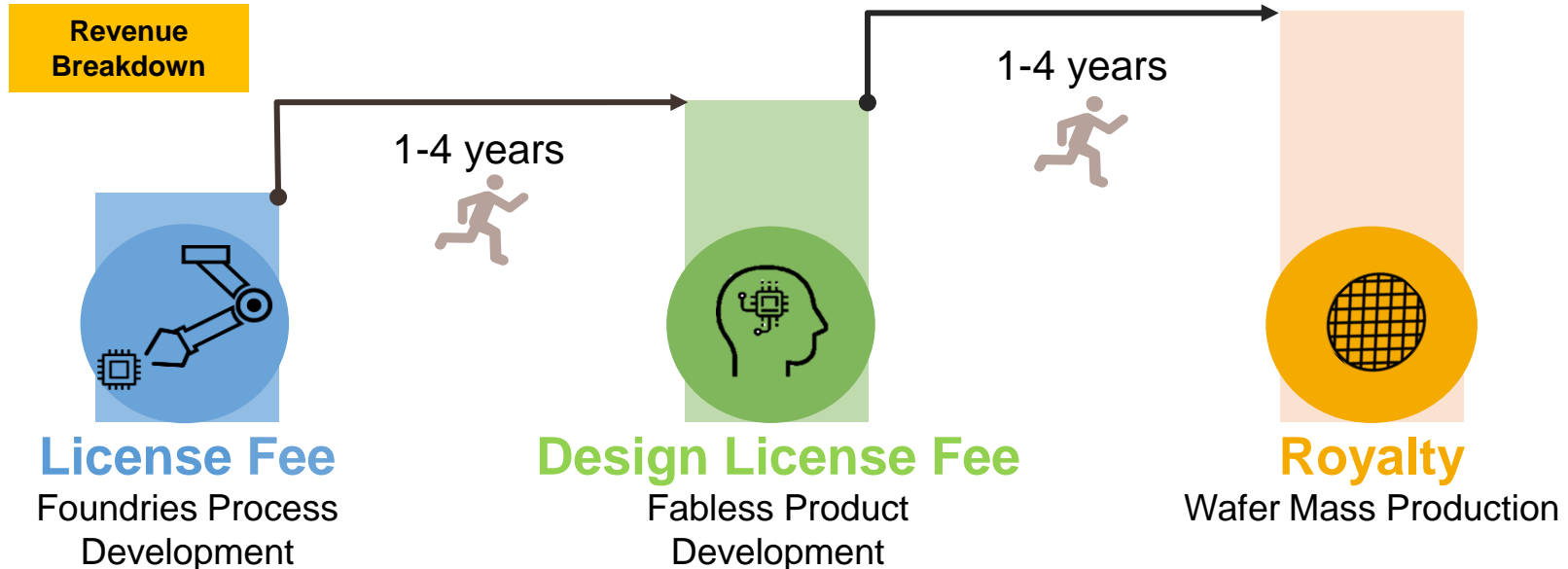


Business Model

- Recurring royalty is the backbone of our business



- 70-75% revenue are from royalty based on wafer production
- More adoption = more volume shipment
- More advanced node wafers = higher ASP per wafer

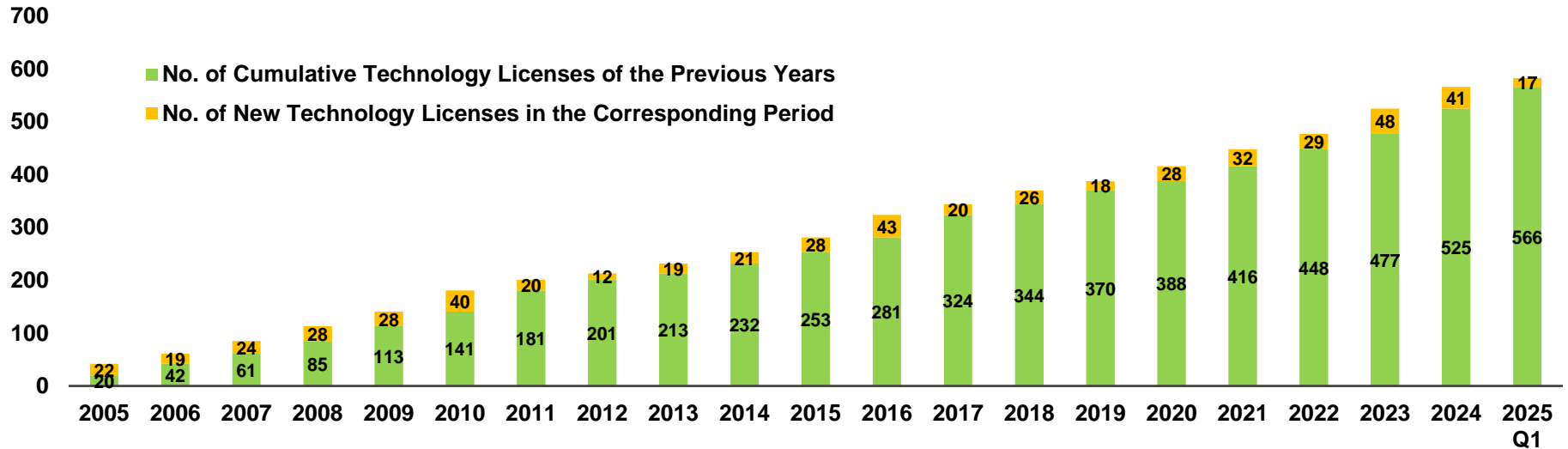


Technology Licenses

Number of Licenses

Year	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025 Q1
License	43	20	26	18	28	32	29	48	41	17

Note: Terms (including number of process platforms and licensing fees) for each technology license are set contractually. Payments are made according to set milestones, and there are no particular seasonal factors involved.



New Technology Under Development

- New technologies are being developed for 188 platforms by Q1 2025.
- 17 licensing contracts were signed.

Technology	2nm	3nm	4/5nm	6/7nm	12/16nm	22/28nm	40nm	55/65nm	80/90nm	0.11~ 0.13um	0.15~ 0.18um	>0.25um
NeoBit	-	-	-	-	-	-	-	1	2	15	11	3
NeoFuse	2	2	1	1	7	23	9	17	9	6	1	-
PUF-Based	-	1	1	1	1	1	-	1	-	1	-	-
MTP	-	-	-	-	1	2	3	11	10	17	27	-

Note: As of March 31st, 2025

Technology Development

▪ Developments by process nodes

12" Fabs	Production	Development	IP Type	Process Type
2nm	0	2	OTP	Nanosheet
3nm	0	3	OTP, PUF	FF, FFP
4/5nm	6	2	OTP, PUF	FF, FF-Auto
6/7nm	4	2	OTP, PUF	FF, FF+
12/16nm	13	9	OTP, PUF, MTP	FF, FF+, FFC, FFC+, LPP, DRAM, HV
22/28nm	60	26	OTP, PUF, MTP	LP/ULP/ULL, HPC/HPC+, HV-OLED, DRAM, SOI, RRAM, MRAM, E-Flash, BCD, WoW
40nm	26	12	OTP, PUF, MTP	LP/ULP, E-Flash, HV-DDI/OLED, ReRAM, BCD+
55/65nm	62	30	OTP, PUF, MTP	LP/ULP, E-Flash, HV-DDI/OLED, DRAM, CIS, BCD, PM
80/90nm	33	17	OTP, MTP	HV-DDI/OLED, LP, Generic, BCD, CIS
0.11/0.13um	23	9	OTP, MTP	HV-DDI, BCD, Generic
0.15/0.18um	13	15	OTP, MTP	BCD, Generic
Total	240	127		

8" Fabs	Production	Development	IP Type	Process Type
80/90nm	9	4	OTP	HV-DDI, LL, BCD
0.11/0.13um	87	30	OTP, PUF, MTP	HV/HV-MR, BCD, LP/LL, CIS, Green, Flash, SOI, Generic, BiCMOS
0.152/0.16/0.18um	257	24	OTP, MTP	HV/HV-MR, BCD, LP/LL, CIS, Green, Generic
0.25um	42	2	OTP	BCD
0.3/0.35um	53	0	OTP, MTP	UHV, BCD
0.4/0.5um	11	1	OTP	UHV, BCD
Total	459	61		

Note: As of March 31st, 2025

THANKS

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For more information, please visit:

eMemory Website: <https://www.ememory.com.tw/>

PUFsecurity Website: <https://www.pufsecurity.com/>

